

#### TOSHIBA INFRASTRUCTURE SYSTEMS & SOLUTIONS CORPORATION

MICROWAVE SOLID-STATE ENGINEERING DEPT. KOMUKAI COMPLEX

1,KOMUKAI-TOSHIBA-CHO,SAIWAI-KU,KAWASAKI 212-8581,JAPAN

PCN: 803-180029 May 21, 2018

# Announcement of PCN (Process Change Notice) of Toshiba Microwave Semiconductor Products

Dear Customers,

We thank you very much for your continuous patronage to our Microwave Semiconductor products. Taking this opportunity, we are glad to inform you that we are going to change the process of the production. We therefore wish to advise you for your understanding and acceptance of this change.

Sincerely yours

— NOTE —

### 1. Applicable product:

All packaged GaAs FET/GaN HEMT enclosed in 7-AA03A package

TIM8996-30 TIM0910-30L

TIM1213-30L TIM1314-30L

TGI9098-100P

Note: Custom parts with above generic part numbers are also applicable.

Ex. TGI1314-30L-xxx

### 2. Description of change:

Change of package outline in Fig.1.

No change of specifications and materials.

# 3. Reason of change:

Change of package processing method by vendor



## 4. Scheduled implementation date and notes:

The change will be implemented with products after "8K1A" date code, October 2018 production.

There still will be products with old package in the distribution (Toshiba Infrastructure Systems & Solutions Corp., Toshiba overseas office and the partner distributors), therefore products with two different types of package will be distributed for a while.

#### 5. Contact:

If you have further question, please feel free to contact our local Toshiba office on this matter.

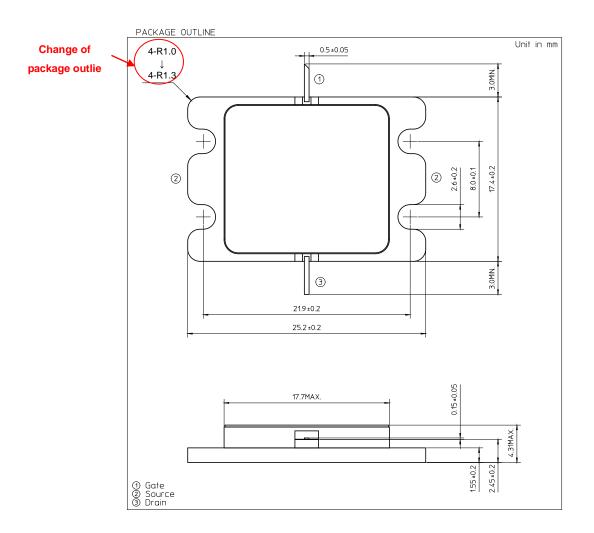


Fig.1 Package Outline